

Amendments to the Claims:

The following listing will replace all prior listing of claims in the application.

Listing of Claims:

CLAIMS

1. (Currently amended) Lithography A lithographic method involving comprising the pressing of a substrate, including the method comprising:

a preparation step during which the a substrate surface (1) is covered with a layer;

a pressing step in which a mold comprising a pattern of recesses and protrusions is pressed so as to penetrate part a portion of the thickness of the aforementioned layer;

at least one attacking etching step in which the layer is attacked etched until parts of the surface of the substrate have been stripped exposed; and an

a substrate etching step, whereby wherein the substrate is etched using an etching pattern which is defined by the mold pattern, which method is characterized in that

wherein the preparation step further comprises a sub-step consisting of the formation of a lower forming an internal sub-layer (2A) of curable material, a step involving the and curing of said the internal sub-layer, and a sub-step consisting of the formation of forming an outer external sub-layer (2B) which is adjacent to the cured internal sub-layer, and

wherein the pressing step including penetration of the above-mentioned further comprises penetrating the protrusions of the mold into this external the external sub-layer until it comes into the protrusions contact with this cured the internal sub-layer.

2. (Currently amended) Method The method according to claim 1, characterized in that this lower wherein the internal sub-layer is formed in contact with

the substrate surface of the substrate and in that wherein, during the attacking at least one etching step, the lower internal sub-layer is removed excavated through in the recesses of the external sub-layer and, during the substrate etching step, the substrate is attacked etched through the same recesses.

3. (Currently amended) Method The method according to claim 1 or claim 2, characterized in that wherein the lower internal sub-layer and the external sub-layer are made of comprise the same material.

4. (Currently amended) Method The method according to any one of claims claim 1 to 3, characterized in that the wherein curing treatment includes the internal sub-layer comprises a heat treatment of the lower internal sub-layer at a temperature higher than its curing temperature, and wherein the pressing step is carried out at a pressing temperature higher than the a glass transition temperature of the external sub-layer.

5. (Currently amended) Method The method according to any one of claims claim 1 to 4, characterized in that wherein the curable material is comprises a polymer.

6. (Currently amended) Method The method according to any one of claims claim 1 to 5, characterized in that wherein the curable material is comprises a resin that can is formulated to be cross-linked.

7. (Currently amended) Method The method according to claim 5 or 6, characterized in that wherein the curable material is comprises one of a negative resin or a positive resin.

8. (Currently amended) Method The method according to any one of claims claim 1 to 7, characterized in that wherein the lower internal sub-layer has a thickness from of 0.01 micron to 1 micron.

9. (Currently amended) Method The method according to any one of claims claim 1 to 8, characterized in that wherein the thickness of the external sub-layer is less than the depth of the pattern recesses of the pattern of the mold.

10. (New) The method according to claim 6, wherein the curable material comprises one of a negative resin or a positive resin.